

A2 3. (Amended) The leadframe of claim 1, wherein the inner perimeter of the paddle ring also includes a plurality of spaced projections.

8. (Amended) The leadframe of claim 1, wherein the paddle ring is generally square shaped and the connection bar is connected to at least one of the terminals of the first row of terminals or the paddle ring at a corner thereof.

A3 9. (Amended) The leadframe of claim 8, further comprising another row of terminals connected to the other side of the connection bar, said another row of terminals for connecting to a second integrated circuit die.

12. (Amended) A semiconductor device, comprising:

a paddle ring having an inner perimeter, an outer perimeter, and a cavity located within the inner perimeter;

A4 a first row of terminals generally surrounding the paddle ring outer perimeter, wherein each of the terminals of the first row of terminals is individually connected to the paddle ring and extends outwardly therefrom;

a second row of terminals surrounding the first row of terminals, wherein each of the terminals of the second row of terminals is connected to a connection bar and wherein the inner row of terminals is connected to the outer row of terminals at a corner of the connection bar; and

an integrated circuit die placed within the cavity and surrounded by the paddle ring, the die including a plurality of die pads that are electrically connected to respective ones of the terminals of the first and second rows of terminals.